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FSA2866 Dual-Host / Dual-SIM Card Crosspoint Analog Switch

Features

Switch Type	2x2 Crosspoint Switch
Input Type	Data
Input Signal Range	0 to V _{CC}
V _{CC}	1.65V to 4.30V
R _{ON}	Data 2Ω (Typical) VSIM 2Ω (Typical)
R _{FLAT}	0.6Ω (Typical)
ESD	IEC 61000-4-2 System Air 15kV, Contact 8kV
Con	28pF (Typical)
C _{OFF}	12pF (Typical)
Package	20-Lead UMLP, 3 x 3 x 0.55mm, 0.40mm Pitch with Exposed DAP
Ordering Information	FSA2866UMX

Description

The FSA2866 is a dual-host, dual-SIM card analog switch designed specifically for cell phones that support two specific carrier services (for example, CDMA and GSM/3G).

Related Resources

- For samples and questions, please contact: Analog.Switch@fairchildsemi.com.
- FSA2866 Evaluation Board

Applications

- MP3 Portable Media Players
- Cellular Phones, Smart Phones

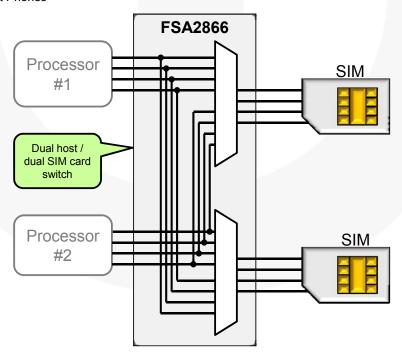


Figure 1. Typical Mobile Phone Application

Pin Descriptions Pin# **Description** Name Type OE. VSIM1 Active Output /SIMH1 1 /OE Input Enable Switch Disabled 2 VSIMH1 1/0 RST1 RSTH1 1/0 3 Common Ports for Host #1 4 CLKH1 1/0 CLK1 DATAH1 1/0 5 CLKH1 VSIMH2 1/0 6 RSTH2 1/0 7 DATA1 Common Ports for Host #2 1/0 8 CLKH2 DATAH1 9 DATAH2 1/0 10 VCC Supply Power 11 **GND** Ground Ground DATA2 1/0 12 CLK2 1/0 13 SIM Card Ports for Card #2 14 RST2 1/0 VSIM2 15 VSIM2 1/0 VSIMH2 16 DATA1 1/0 17 CLK1 1/0 SIM Card Ports for Card #1 RST2 1/0 18 RST1 RSTH2 19 VSIM1 1/0 CLK2 Host #1 connected to Card #1 [VSIMH1=VSIM1; DATA2 DATAH1=DATA1; DATAH2 CLKH1=CLK1; RSTH1=RST1] SEL=0 Host #2 connected to Card #2 Figure 2. Functional Diagram **IVSIMH2=VSIM2:** DATAH2=DATA2; SEL VSIM² RST1 DATA1 CLKH2=CLK2; 20 19 18 17 16 RSTH2=RST2] Control 20 SEL Input Pin /OE VSIM2 15 Host #1 connected to Card #2 **IVSIMH1=VSIM2:** VSIMH1 2 14 RST2 DATAH1=DATA2; CLKH1=CLK1; RSTH1=RST1] CLK2 3 Exposed DAP 13 RSTH1 SEL=1 Host #2 connected to Card #1 CLKH1 DATA2 4 12 IVSIMH2=VSIM1: DATAH2=DATA1; DATAH1 5 11 GND CLKH2=CLK1; RSTH2=RST1] 8 9 10 7 Exposed die attach paddle (DAP) not CLKH2 DAP DAP N/C RSTH2 DATAH2 electrically connected to any pin. Figure 3. Pin Assignments (Top Through View)

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Min.	Max.	Unit	
V _{CC}	Supply Voltage		-0.50	+5.5	V
V _{CNTRL}	DC Input Voltage (SEL,/OE)		-0.5	V _{CC}	V
V_{SW}	DC Switch I/O Voltage - DATAHn, CLKHn, CLKn, R	RSTHn, RSTn	-0.5	V _{CC} + 0.3	V
I _{IK}	DC Input Diode Current		-50		mA
I _{SIM}	DC Output Current – VSIMHn, VSIMn			100	mA
I _{оит}	DC Output Current - DATAHn, CLKHn, CLKn, RST	Hn, RSTn		35	mA
T _{STG}	Storage Temperature		-65	+150	°C
		All Pins	8		
	Human Body Model, JEDEC: JESD22-A114	I/O to GND, Card Side Pins	16		
FCD		Power to GND	9		147
ESD	Charged Device Model, JEDEC: JESD22-C101		2		kV
	IFC 61000 4.2 System Level	Contact	8		
	IEC 61000-4-2 System-Level	Air Gap	15		

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding these ratings or designing to Absolute Maximum Ratings.

Symbol I	Symbol Parameter			Max.	Unit
V _{CC}	Supply Voltage	1.65		4.3	V
V _{CNTRL}	Control Input Voltage (SEL, /OE)	0		V _{CC}	V
V _{SW}	Switch I/O Voltage - DATAHn, CLKHn, CLKn, RSTHn, RSTn	0		V _{CC}	V
I _{SIM}	DC Output Current – VSIMHn, VSIMn			30	mA
I _{OUT}	OUT DC Output Current – DATAHn, CLKHn, CLKn, RSTHn, RSTn			10	mA
T _A	Operating Temperature	-40		+85	°C

DC Electrical Characteristics

 T_A =25°C and V_{CC} =3.0V unless otherwise noted.

Symbol	Parameter	Conditions V _{cc} (V)		T _A =- 40°C to +85°C		Unit	
				Min.	Ту р.	Max.	
VıK	Clamp Diode Voltage	I _{IN} =-18mA	2.7			-1.2	V
			1.65 to 2.30	1.1			
V _{IH}	Input Voltage High		2.7 to 3.6	1.3			V
			4.3	1.7			
			1.65 to 2.30			0.4	
V_{IL}	Input Voltage Low		2.7 to 3.6			0.5	V
			4.3			0.7	
I _{IN}	Control Input Leakage (SEL,/OE)	V _{SW} =0 to V _{CC}	4.3	-1		1	μA
I _{NO(OFF)}	Off Leakage Current of Ports RSTn, DATAn, CLKn, VSIMn	VSIMHn=DATAHn=CLKHn=RSTHn=0.3 V, V _{CC} -0.3V; RSTn, CLKn, DATAn, or VSIMn=V _{CC} -0.3V, 0.3V, or Floating	4.3	-100		100	nA
I _{A(ON)}	On Leakage Current of Common Ports – RSTHn, DATAHn, CLKHn, VSIMHn	Common=0.3V, V _{CC} -0.3V; VSIMHn=DATAHn=CLKHn=RSTHn= V _{CC} -0.3V, 0.3V, or Floating	4.3	-100		100	nA
I _{OFF}	Power-Off Leakage Current	VSIMHn or DATAHn or CLKHn or RSTHn V_{IN} =0V to 4.3V, V_{CC} =0V	0	-2		2	μΑ
l _{OZ}	Off-State Leakage	VSIMHn or DATAHn or CLKHn or RSTHn V_{IN} =0.3V to 4.3V, I OE= I CC	4.3	-5		5	μΑ
R _{ON_DATA}	Switch On Resistance for Data Paths	I _{ON} =-20mA; /OE=0V; SEL=V _{CC} or 0V; RSTn, CLKn, DATAn, or VSIMn=0 or 2.7V	2.7		2.0	3.5	Ω
R _{ON_VSIM}	Switch On Resistance for VSIM Paths	I _{ON} =- 50mA; /OE=0V; SEL=V _{CC} or 0V; RSTn, CLKn, DATAn, or VSIMn=0 or 2.7V	2.7		2.0	3.5	Ω
ΔR_{ON_DATA}	On Resistance Matching Between Data Channels	I _{ON} =-20mA; /OE=0V; SEL=V _{CC} or 0V; RSTn, CLKn, or DATAn=0V	2.7		0.10	0.25	Ω
R _{ON_FLAT}	On Resistance Flatness Data Path Signals	I_{ON} =-20mA, /OE=0V,SEL=V _{CC} or 0V, RSTn, CLKn or DATAn=0 to V _{CC}	2.7		0.6	0.8	Ω
Icc	Quiescent Supply Current	V _{IN} =0 or V _{CC} , I _{OUT} =0	4.3			1	μA
I _{CCT}	Increase in I _{CC} Current Per Control Voltage and V _{CC}	V _{IN} =1.65V, V _{CC} =4.3V	4.3		7	9.5	μA

Notes:

- 1. Guaranteed by characterization; not production tested.
- 2. On resistance is determined by the voltage drop between the D+/D- and D+/R, D-/L pins at the indicated current through the switch.
- 3. $\Delta R_{ON} = R_{ON_max} R_{ON_min}$ measured at identical V_{CC} , temperature, and voltage.

AC Electrical Characteristics

 T_A =25°C and V_{CC} =3.0V unless otherwise noted.

Cumbal	Barameter	O a maliki a ma	V 00	T _A =- 40°C to +85°C			11:4:4
Symbol	Parameter	Conditions	V _{cc} (V)	Min.	Ту р.	Max.	Unit
4	Turn On Time /OF to Output	R _L =50Ω, C _L =30pF, V _{SW} =0.8V	2.8 to 4.3		55	75	20
ton	Turn-On Time, /OE to Output	n Time, /OE to Output Figure 4 1.8			110	ns	
+	Turn Off Time /OF to Output	$R_L=50\Omega$, $C_L=30pF$, $V_{SW}=0.8V$	2.8 to 4.3		24	75	no
t _{OFF}	Turn-Off Time, /OE to Output	Figure 4	1.8			110	ns
t _{BBM}	Break-Before-Make Time	R_L =50 Ω , C_L =30pF, V_{SW} =0.8V Figure 5		2	35		ns
O _{IRR}	Off Isolation	R_L =50 Ω , f=100KHz, /OE=V _{CC} , V_{SW} =13dBm (3V _{pp}) Figure 6	1.8 to 4.3		90		dB
X _{TALK}	Crosstalk	R_L =50 Ω , f=100KHz, V_{SW} =13dBm (3 V_{pp}) Figure 6	1.8 to 4.3		85		dB
	-3db Bandwidth	$R_L=50\Omega$, $C_L=0$ pF, Figure 8			210		
BW		R_L =50 Ω , C_L =5pF, Figure 8	3.0		198		MHz
		R_L =50 Ω , C_L =30pF, Figure 8	3.0		120		1011 12
		R_L =50 Ω , C_L =50pF, Figure 8			78		

Note:

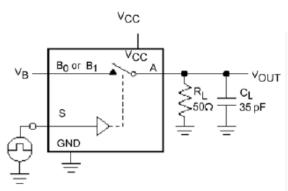
4. Guaranteed by characterization; not production tested.

Capacitance

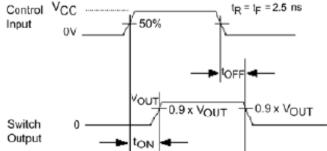
T_A=25°C unless otherwise noted.

Symbol	Darameter	Conditions	T _A =- 40°C to +85°C			Unit
Symbol Paramete	Parameter	Conditions	Min. Ty p. Max.			
C _{IN}	Control Pin Input Capacitance	V _{CC} =0V, f=1MHz		2	7	pF
C _{ON}	On Capacitance	V _{CC} =3.3V, /OE=0V, f=1MHz, Figure 7		28		pF
C _{OFF}	Off Capacitance	V _{CC} and /OE=3.3V, f=1MHz, Figure 7		12	- y	pF

AC Loadings and Waveforms

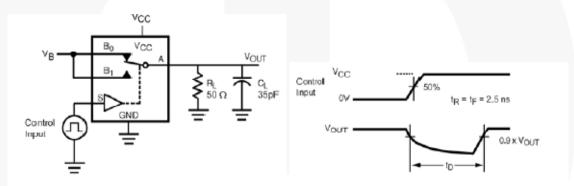


C_L includes Fixture and Stray Capacitance



Logic Input Waveforms Inverted for Switches that have the Opposite Logic Sense

Figure 4. Turn-On / Turn-Off Timing



C_L Includes Fixture and Stray Capacitance

Figure 5. Break-Before-Make Timing

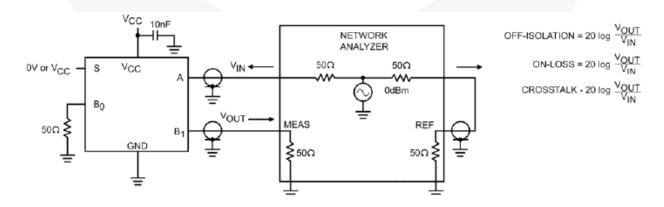


Figure 6. Off Isolation and Crosstalk

AC Loadings and Waveforms (Continued)

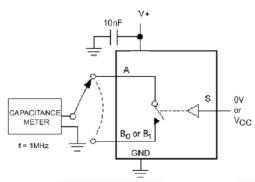


Figure 7. On / Off Capacitance Measurement Setup

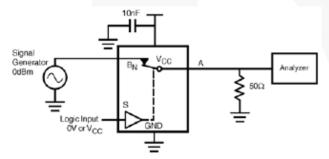
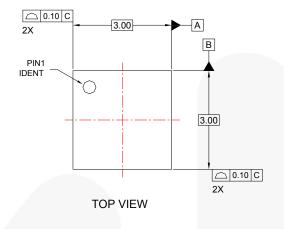
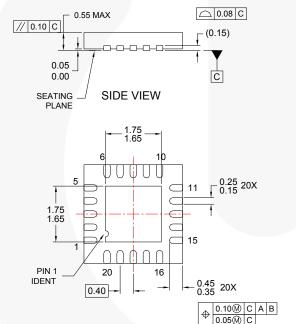
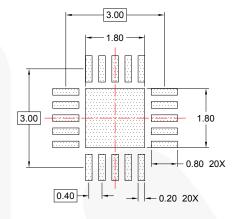


Figure 8. Bandwidth

Physical Dimensions







RECOMMENDED LAND PATTERN

NOTES:

- A. PACKAGE CONFORMS TO JEDEC MO-248 VARIATION UEEE.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
- D. LAND PATTERN RECOMMENDATION IS FROM PCB MATRIX CALCULATOR V2009.
- E. DRAWING FILENAME: MKT-UMLP20Brev1.

BOTTOM VIEW

Figure 9. 20-Pin Ultrathin Molded Leadless Package (UMLP)

Order Number	Operating Temperature Range	Package Description	Packing Method
FSA2866UMX	-40 to 85°C	20-Lead Ultrathin Molded Leadless Package (UMLP)	Tape & Reel

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Definition of Terms		
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